

What Is Claimed Is:

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1. An adhesive composition, comprising:
  - an insulating resin;
  - a photopolymerization initiator; and
  - an oxetan compound.

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2. The adhesive composition according to Claim 1, comprising 5 to 50 wt% oxetan compound in 100 wt% adhesive composition.

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3. The anisotropic conductive adhesive composition according to Claim 1 or claim 2, further comprising electrically conductive particles.

4. A connected structure, wherein electrodes on a plastic substrate and on a circuit board that are facing each other are connected by the adhesive composition according to Claim 1 any of Claims 1 to 3.

Claim 1  
any of claims 1 to 3.

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